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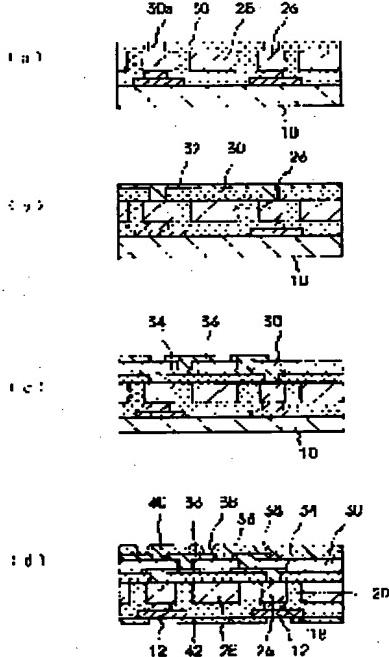
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(54) MULTILAYER WIRING BOARD AND ITS MANUFACTURE

(57)Abstract:

PROBLEM TO BE SOLVED: To provide a multilayer wiring board, in which a continuity part penetrating a core board can be formed with a high density and which is superior in thermal radiation and electrical characteristics.

SOLUTION: Wiring patterns 34 and 36 are formed on both sides or one side of a core board, and a continuity part penetrating the core board is connected electrically with the wiring pattern. In such a multilayer wiring board, the core board is comprises of a conductor part, consisting of a via column 26 formed by plating and a conductor core part 28 and an insulator part 20 for electrically insulating the via column 26 and the conductor core part 28. After the wiring pattern is formed on the core board, the conductor board 10 is removed so as to obtain the multilayer board.



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